

ABSTRACTCONNECTION PAD ARRANGEMENTS FOR ELECTRONIC CIRCUIT  
COMPRISING BOTH FUNCTIONAL LOGIC AND FLASH-EEPROM

An integrated circuit (IC1) comprising functional logic (1) and  
5 Flash-EEPROM (2) coupled, via mixing devices (IMUX, OMUX), to  
connection pads (CP1, CP2), which are arranged into pad arrangements  
(PAD: PAD1, PAD2, PAD3, PAD4). Each pad arrangement (PAD) comprises  
two juxtaposed connection pads (CP1, CP2) interconnected electrically and  
having substantially the same design. In this way, many "probing" are  
10 possible on a same pad arrangement, while probing at most two times each  
connection pad thereof.. By probing at most two times on a connection pad,  
a good "bondability" of the pad is assured. This is particularly useful in the  
present case of combined functional logic and the Flash-EEPROM where  
three probings are generally required for the flash test of the EEPROM, the  
15 digital test of the functional logical and the analog test of the latter. In a  
preferred embodiment, the integrated circuit (IC2) comprises a first set of  
dedicated connection pads (PAD10, PAD11, PAD12) coupled to the  
functional logic (1), and a distinct second set of dedicated connection pads  
(PAD21, PAD22) coupled to the Flash-EEPROM (2).

20

Fig. 2